

# LOCTITE ECCOBOND FP0097

September 2012

## PRODUCT DESCRIPTION

LOCTITE ECCOBOND FP0097 provides the following product characteristics:

|                              |   |
|------------------------------|---|
| <b>Technology</b>            | Epoxy   |
| <b>Appearance</b>            | Black   |
| <b>Product Benefits</b>      | <ul style="list-style-type: none"> <li>• High purity</li> <li>• Low ionic impurities</li> <li>• Improved wet adhesion</li> <li>• Excellent moisture resistance</li> <li>• Good thermal stability</li> <li>• High flow properties</li> <li>• Forms a rigid, low stress seal</li> </ul> |
| <b>Cure</b>                  | Heat cure   |
| <b>Application</b>           | Encapsulant   |
| <b>Operating Temperature</b> | -65 to 150 °C   |

LOCTITE ECCOBOND FP0097 high performance liquid epoxy encapsulant is designed to dissipate stress and extend thermal cycling performance. Autoclave performance on live devices is greater than 1,000 hours with no failure, depending upon device and package type. LOCTITE ECCOBOND FP0097 features filler with 25micron maximum particle size, giving it improved handling properties for fine wire pitch applications.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

|   |        |
|---|--------|
| Viscosity, Brookfield - RVF, 25 °C, mPa·s (cP):   |        |
| Spindle 6, speed 20 rpm                           | 20,000 |
| Filler Content, % Ignition                        | 73     |
| Pot Life @ 25 °C (time to double viscosity), days | 4      |
| Gel Time @ 121°C, minutes                         | 11     |
| Shelf Life @ -40°C, days                          | 274    |
| Flash Point - See SDS                             |        |

## TYPICAL CURING PERFORMANCE

### Recommended Cure Schedule

30 minutes @ 125°C plus

90 minutes @ 165°C

*Designed to be used with packages which are affected by higher levels of stress. This cure will give optimum properties.*

### Alternate Cure Schedule

1 hour @ 110°C plus

3 hours @ 165°C

*Designed for robust packages which are not sensitive to stress.*

### Substrate Temperature

Temperature, °C 90

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties :

|   |   |
|---|---|
| Coefficient of Thermal Expansion , ppm/°C:        |   |
| Below Tg (40 to 120°C)                            | 21  |
| Above Tg (190 to 220°C)                           | 72  |
| Glass Transition Temperature (Tg), °C             | 149   |
| Extractable Ionic Content, ppm:                   |   |
| Chloride (Cl-)                                    | <2  |
| Sodium (Na+)                                      | <1  |
| Flexural strength                                 | N/mm <sup>2</sup> 113<br>(psi) (16,385)       |
| Flexural Modulus                                  | N/mm <sup>2</sup> 11,500<br>(psi) (1,667,500) |
| Alpha Particle Emissions, cts/cm <sup>2</sup> /hr | 0.001   |

## GENERAL INFORMATION

**For safe handling information on this product, consult the Safety Data Sheet, (SDS).**

### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

### THAWING:

1. Frozen packages must be completely thawed before use.
2. Store tip down and warm at room temperature until no longer cool to the touch (normally 60 to 90 minutes).
3. DO NOT thaw in an oven.

### DIRECTIONS FOR USE

1. A positive displacement pump is recommended for reproducible shot sizes.
2. An 18 to 20gauge tapered tip needle should be used for easy dispensing.
3. For best results, the material should be dispensed onto a substrate that has been preheated to approximately 90°C and held at that temperature until flow stops.
4. Moisture curing begins immediately after product is exposed to the atmosphere. Parts should be assembled within a few minutes after the product is applied.
5. The cured properties of moisture contaminated material will be poorer than those described.
6. **NOTE:** Elevated temperatures reduce working life.

## STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

## Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$

$\text{kV/mm} \times 25.4 = \text{V/mil}$

$\text{mm} / 25.4 = \text{inches}$

$\text{N} \times 0.225 = \text{lb}$

$\text{N/mm} \times 5.71 = \text{lb/in}$

$\text{psi} \times 145 = \text{N/mm}^2$

$\text{MPa} = \text{N/mm}^2$

$\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$

$\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$

$\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$

$\text{mPa}\cdot\text{s} = \text{cP}$

## Disclaimer

### Note

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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